



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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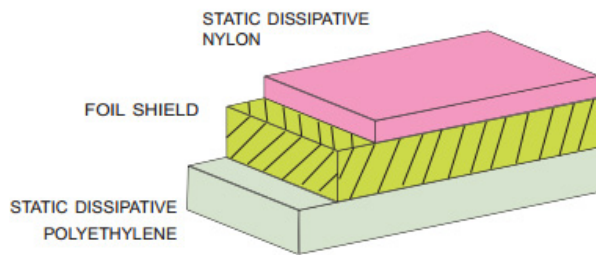
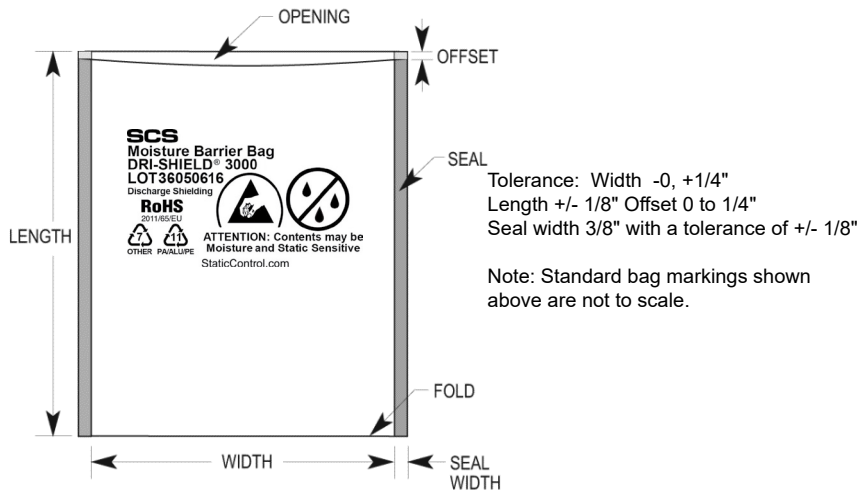
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Moisture Barrier Bag Dri-Shield® 3000

This foil moisture barrier bag provides protection for ESD sensitive and moisture sensitive electronics, typically SMT (Surface Mount Technology) items. Best practice is to use with Desiccant and a Humidity Indicator Card. A nylon layer helps to strengthen the bag. The bags are heat sealable and suitable for vacuum packaging. Bags are printed with ESD protective and moisture sensitive warning symbols, and a lot code for traceability.

SCS Moisture Barrier Bags Dri-Shield® 3000 are manufactured from a laminate of nylon, foil, and polyethylene. The metal layer provides discharge shielding and minimizes the penetration of electric fields and electrostatic discharges.



SCS Moisture Barrier Bags are packaged in a polyethylene bag.

RoHS 2, REACH, and Conflict Minerals Statement

None of the RoHS 2 restricted materials or REACH substances of very high concern as of 2017/01/12, or Conflict Minerals are intentionally added in manufacturing this product. Ref: European Union Directive 2011/65/EU and Regulation (EC) No. 1907/2006/CE. See [SCS Warranty, Limitation of Liability and Remedies](#)

Meets ANSI/ESD S20.20, Packaging standard ANSI/ESD S541, Static Control Bag ANSI/ESD S11.4 Level 1, and IPC/JEDEC J-STD-033.



Physical	Typical Value	Testing Method
Moisture Vapor Transmission Rate (MVTR)	≤ 0.0003 grams/100 sq. in./24 hrs ≤ 0.002 grams/100 sq. in./24hrs	ASTM F1249 ASTM F392 condition E and ASTM F2149
Tensile Strength	3800 PSI, 26 MPa	ASTM D882
Puncture Resistance	16 lbs, 71 N	MIL-STD-3010C Method 2065
Seal Strength	15 lbs, 66 N	ASTM D882
Thickness	6 mils, 0.006" +/-10%	MIL-STD-3010C Method 1003
Marking Adhesion	Pass	IPC-TM-650 2.4.1

Electrical	Typical Value	Testing Method
ESD Shielding	<10 nJ	ANSI/ESD STM11.31
Surface Resistance - Interior	1 x 10 ⁴ to < 1 x 10 ¹¹ ohms	ANSI/ESD STM11.11
Surface Resistance - Exterior	1 x 10 ⁴ to < 1 x 10 ¹¹ ohms	ANSI/ESD STM11.11
EMI Attenuation	45 dB	1 to 10 GHz

Cleanliness	Typical Value	Testing Method
Silicone	Not Detected	FTIR

Heat Sealing Conditions	Typical Value
Temperature	400°F, 204°C
Time	0.6 – 4.5 seconds
Pressure	30 – 70 PSI, 206 – 482 KPa

Bag is free of amines, silicones and heavy metals.

This product is intended for commercial use only. This product is not on the Qualified Product Listing under the Defense Standardization Program.

NOTE: The complete dry package concept of packaging for electronics requires three elements:

[Moisture Barrier Bags](#) - To Protect

[Desiccants](#) - To Absorb Moisture

[Humidity Indicator Cards](#) - To Monitor Performance

Made in the United States of America with Globally Sourced Materials.

Specifications and procedures subject to change without notice.

DRI-SHIELD® 3000 MOISTURE BARRIER BAG

926 JR Industrial Drive, Sanford, NC 27332
WEB SITE: StaticControl.com
PHONE (919) 718-0000

DRAWING NUMBER
Dri-Shield® 3000

DATE
April
2017

